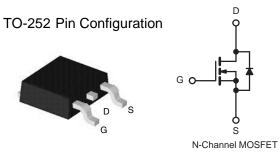


DTU09N03S www.din-tek.jp

### N-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)			
30	0.0125 at V <sub>GS</sub> = 10 V	55 <sup>d</sup>	18.2			
50	0.0163 at V_{GS} = 4.5 V	45 <sup>d</sup>	10.2			



Top View

#### **FEATURES**

- DT-Trench Power MOSFET
- 100 % R<sub>g</sub> and UIS Tested
- Compliant to RoHS Directive 2002/95/EC

#### **APPLICATIONS**

- Power Supply
  Secondary Synchronous Rectification
- DC/DC Converter

ABSOLUTE MAXIMUM RATINGS	$T_{\rm C} = 25$ C, unless our			1	
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V <sub>DS</sub>	30	v		
Gate-Source Voltage		V <sub>GS</sub>		± 20	
Continuous Drain Current (T <sub>1</sub> = 150 °C)	T <sub>C</sub> = 25 °C	I <sub>D</sub>	55 <sup>d</sup>	А	
Continuous Diain Current (1) = 150°C)	T <sub>C</sub> = 70 °C	D'	45 <sup>d</sup>		
Pulsed Drain Current		I <sub>DM</sub>	165	A	
Avalanche Current	I <sub>AS</sub>	34			
Single Avalanche Energy <sup>a</sup>	L = 0.1 mH	E <sub>AS</sub>	78	mJ	
Marian Diasia di stand	T <sub>C</sub> = 25 °C	D	55.5 <sup>b</sup>	W	
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 25 °C <sup>c</sup>	- P <sub>D</sub> -	2.7		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Limit	Unit		
Junction-to-Ambient (PCB Mount) <sup>c</sup>	R <sub>thJA</sub>	54	°C/W		
Junction-to-Case (Drain)	R <sub>thJC</sub>	2.7			

Notes:

a. Duty cycle  $\leq$  1 %.

b. See SOA curve for voltage derating.

c. When mounted on 1" square PCB (FR-4 material).

d. Package limited.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{DS} = 0 V, I_{D} = 250 \mu A$	30	30			
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \ \mu A$	1		3	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS}$ = 0 V, $V_{GS}$ = ± 20 V			± 250	nA	
		$V_{DS}$ = 30 V, $V_{GS}$ = 0 V			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS}$ = 30 V, $V_{GS}$ = 0 V, $T_{J}$ = 125 °C			50	μA	
		$V_{DS}$ = 30 V, $V_{GS}$ = 0 V, $T_{J}$ = 150 °C			250		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 10$ V, $V_{GS}$ = 10 V	55			А	
Drain-Source On-State Resistance <sup>a</sup>	D	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 12 A		0.0125	0.0157		
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 10 A		0.0163	0.0179	Ω	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A		100		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			578		pF	
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 15 V, f = 1 MHz		364			
Reverse Transfer Capacitance	C <sub>rss</sub>			210			
Total Gate Charge <sup>c</sup>	Qg	$V_{DS}$ = 15 V, $V_{GS}$ = 10 V, $I_{D}$ = 20 A		34 56			
				20.1	30.2	nC	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{\rm DS}$ = 15 V, $V_{\rm GS}$ = 4.5 V, $I_{\rm D}$ = 20 A		6			
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			5.7			
Gate Resistance	Rg	f = 1 MHz	0.4	2	4	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			8	16		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 15 V, R <sub>I</sub> = 1.5 $\Omega$		9	18		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 10$ Å, $V_{GEN}$ = 10 V, $R_g$ = 1 $\Omega$		35	53	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>			9	18		
Drain-Source Body Diode Ratings a	nd Characteris	stics T <sub>C</sub> = 25 °C <sup>b</sup>	•	•			
Continuous Current	ا <sub>S</sub>				55	٨	
Pulsed Current	I <sub>SM</sub>				165	A	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = 10 A, V <sub>GS</sub> = 0 V		0.75	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>			34	51	ns	
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>	I <sub>F</sub> = 10 A, dl/dt = 100 A/µs		2	3	А	
Reverse Recovery Charge	Q <sub>rr</sub>			34	51	nC	

Notes:

a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

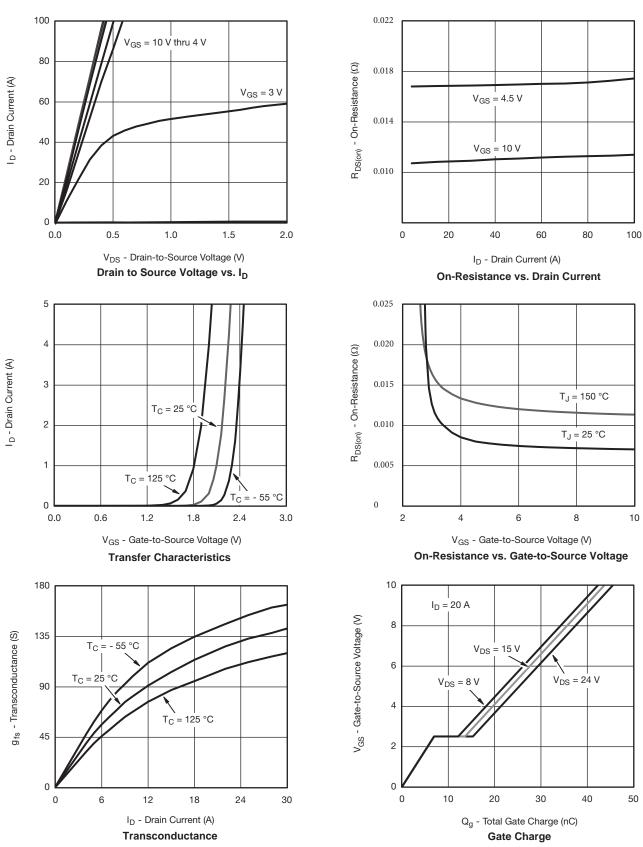
b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

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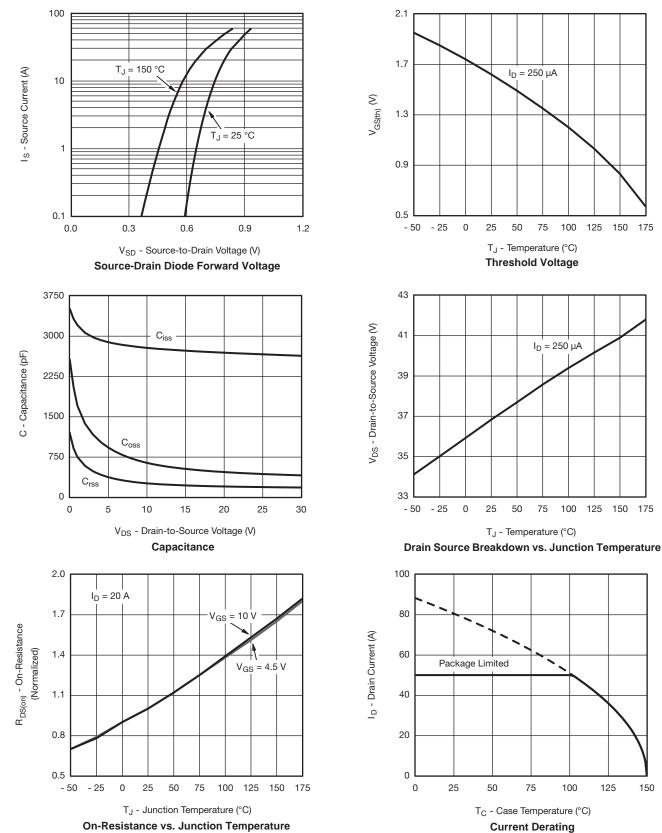


#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

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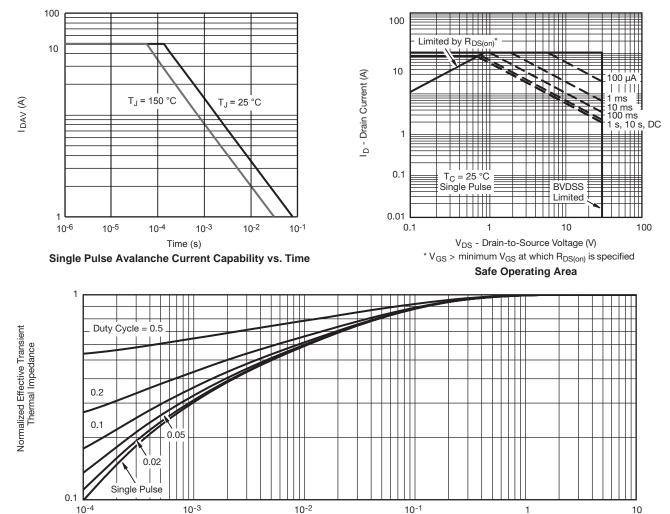
150





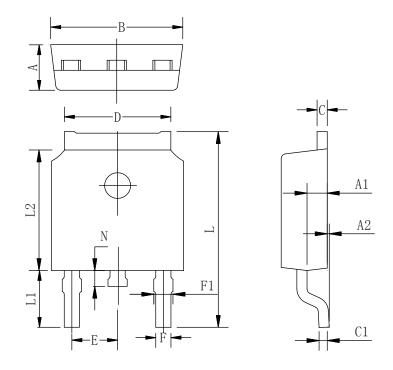
#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

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Square Wave Pulse Duration (s) Normalized Thermal Transient Impedance, Junction-to-Case

## TO-252-2L PACKAGE OUTLINE



#### COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

Symbol	Min	Тур	Max	
A	2.10	2.30	2.50	
Al	0.88	1.01	1.16	
A2	0.00	0.15	0.28	
В	6.40	6.60	6.80	
С	0.42	0.50	0.63	
C1	0.42	0.50	0.63	
D	5.08	5.32	5.65	
E		2.286 TYP		
F	0.63	0.76	0.89	
F1	0.64	0.86	1.08	
L	9.30	9.90	10.80	
L1	2.4	2.8	3.6	
L2	5.90	6.10	6.55	
N	0.57	0.80	1.05	

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